

# TECHNICAL MANUAL

## LSI53C180 Ultra160 SCSI Bus Expander

*Version 1.3*

**June 2001**

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# Preface

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This manual provides a description of the LSI53C180 Ultra160 SCSI Bus Expander chip that supports all combinations of Single-Ended and Low Voltage Differential SCSI bus conversions.

Currently the LSI53C140 is offered in a 192-BGA package so that customers who are designing Ultra2 can easily upgrade to Ultra160. Refer to System Engineering Note S11006 for design considerations using the LSI53C140 and LSI53C180.

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## **Audience**

This manual assumes some prior knowledge of current and proposed SCSI standards. For background information, please contact:

### **ANSI**

11 West 42nd Street  
New York, NY 10036  
(212) 642-4900  
Ask for document number X3.131-199X (SCSI-2)

### **Global Engineering Documents**

15 Inverness Way East  
Englewood, CO 80112  
(800) 854-7179 or (303) 397-7956 (outside U.S.)  
FAX (303) 397-2740  
Ask for document number X3.131-1994 (SCSI-2) or  
X3.253 (*SCSI Parallel Interface-3 (SPI-3)*)

## **ENDL Publications**

14426 Black Walnut Court  
Saratoga, CA 95070  
(408) 867-6642

Document names: *SCSI Bench Reference*, *SCSI Encyclopedia*,  
*SCSI Tutor*

## **Prentice Hall**

113 Sylvan Avenue  
Englewood Cliffs, NJ 07632  
(800) 947-7700

Ask for document number ISBN 0-13-796855-8,  
*SCSI: Understanding the Small Computer System Interface*

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## **Organization**

This document has the following chapters and appendixes:

- **Chapter 1, Introduction**, contains the general information about the LSI53C180 product.
- **Chapter 2, Functional Descriptions**, describes the main functional areas of the chip in more detail, including the interfaces to the SCSI bus and external memory.
- **Chapter 3, Specifications**, contains the pin diagram, signal descriptions, electrical characteristics, AC timing diagrams, and mechanical drawing of the LSI53C180.
- **Appendix A, Wiring Diagrams**, contains wiring diagrams that show typical LSI53C180 usage.
- **Appendix B, Glossary**, contains commonly used terms and their definitions.

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## Revision Record

<b>Date</b>	<b>Version</b>	<b>Remarks</b>
2/00	1.0	Version 1.0
11/00	1.1	All product names changed from SYM to LSI.
4/01	1.2	Changes in Chapter 2 to how Warm Swap Enable is designated. Changes in Chapter 3 to DC Characteristics.
6/01	1.3	Changes to wiring diagrams in Appendix A.



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# Chapter 1

## Introduction

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This chapter describes the LSI53C180 Ultra160 SCSI Bus Expander and its applications. It includes these sections:

- [Section 1.1, “General Description,” page 1-1](#)
- [Section 1.2, “Ultra160 SCSI,” page 1-6](#)

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### 1.1 General Description

The LSI53C180 Ultra160 SCSI Bus Expander is a single chip solution allowing the extension of SCSI device connectivity and/or cable length limits. A SCSI bus expander couples bus segments together without any impact to the SCSI protocol, software, or firmware. The LSI53C180 Ultra160 SCSI Bus Expander connects Single-Ended (SE) Ultra and Low Voltage Differential (LVD) Ultra160 peripherals together in any combination. The LSI53C180 does not support High Voltage Differential (HVD) mode.

The LSI53C180 is capable of supporting any combination of SE or LVD bus mode on either the A or B Side port. This provides the system designer with maximum flexibility in designing SCSI backplanes to accommodate any SCSI bus mode. The LSI53C180 has independent RBIAS pins allowing margining for each bus. A 10 k $\Omega$  pull-up resistor on RBIAS is required to provide the correct LVD levels.

**Figure 1.1 LSI53C180 SCSI Bus Modes**

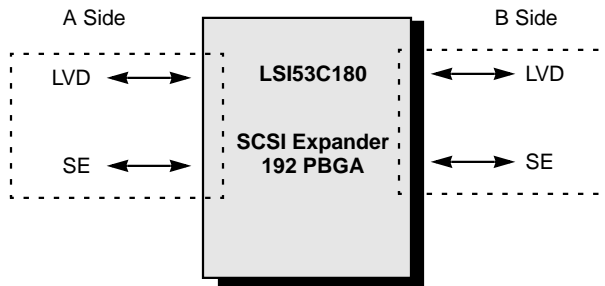


Figure 1.1 shows the two SCSI bus modes available on the A or B Side. LVD Link™ transceivers provide the multimode LVD or SE capability. The LSI53C180 operates as both an expander and converter. In both SCSI Bus Expander and Converter modes, cable segments are isolated from each other. This feature maintains the signal integrity of each cable segment.

Table 1.1 shows the types of operational modes for the LSI53C180.

**Table 1.1 Types of Operation**

Signal Type	Speed
LVD to LVD	Ultra160
SE to SE	Ultra
LVD to SE	Ultra
SE to LVD	Ultra

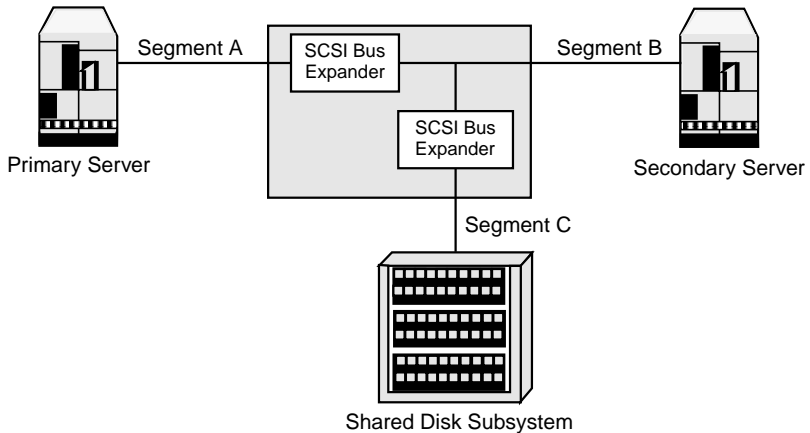
The LSI53C180 provides additional control capability through the pin level isolation mode (Warm Swap Enable). This feature permits logical disconnection of both the A Side bus and the B Side bus without disrupting SCSI transfers currently in progress. For example, devices on the logically disconnected B Side can be swapped out while the A Side bus remains active.

The LSI53C180 is based on previous bus expander technology, which includes signal filtering along with retiming to maintain skew budgets. The LSI53C180 is independent of software.

## 1.1.1 Applications

- Server clustering environments
- Expanders creating distinct SCSI cable segments that are isolated from each other

**Figure 1.2 LSI53C180 Server Clustering**



[Figure 1.2](#) demonstrates how SCSI bus expanders are used to couple bus segments together without any impact on the SCSI protocol or software. Configurations that use the LSI53C180 SCSI Bus Expander in the Ultra160 mode (LVD to LVD) allow the system designer to take advantage of the inherent cable distance, device connectivity, data reliability, and increased transfer rate benefits of LVD signaling with Ultra160 SCSI peripherals.

In the [Figure 1.2](#) example, two LSI53C180 expanders are used to configure three segments. This configuration allows segment A to be treated as a point-to-point segment. Segments B and C are treated as load segments with at least 8 inches between every node. [Table 1.2](#) shows the various distance requirements for each SCSI bus mode.

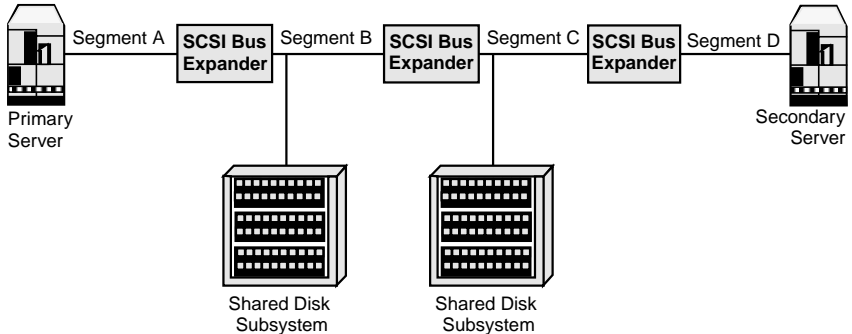
**Table 1.2 SCSI Bus Distance Requirements**

Segment	Mode	Length Limit
A	LVD (Ultra160)	25 meters
	SE (Ultra)	3 meters <sup>1</sup>
B	LVD (Ultra160)	12 meters
	SE (Ultra)	1.5 meters
C	LVD (Ultra160)	12 meters
	SE (Ultra)	1.5 meters

1. The length may be more, possibly 6 meters, as no devices are attached to it.

In the second example, [Figure 1.3](#), the LSI53C180 is cascaded to achieve four distinct SCSI segments. Segments A and D can be treated as point-to-point segments. Segments B and C are treated as load segments with at least 8-inch spacing between every node.

**Figure 1.3 LSI53C180 SCSI Bus Device**



**Table 1.3 Transmission Mode Distance Requirements**

Segment	Mode	Length Limit
A, D	LVD (Ultra160)	25 meters
	SE (Ultra)	1.5 meters
B, C	LVD (Ultra160)	12 meters
	SE (Ultra)	1.5 meters

## 1.1.2 Features

- A flexible SCSI bus expander that supports any combination of LVD or SE transceivers
- Creates distinct SCSI bus segments that are isolated from each other
- Integrated LVD Link transceivers for direct attachment to either LVD or SE bus segments
- Operates as a SCSI Bus Expander
  - LVD to LVD (Ultra160 SCSI)
  - SE to SE (Ultra SCSI)
- Operates as a SCSI Bus Converter
  - LVD to SE (Ultra SCSI)
  - SE to LVD (Ultra SCSI)
- Targets and initiators may be located on either the A or B Side of the device
- Accepts any asynchronous or synchronous transfer speed up to Ultra160 SCSI (for LVD to LVD mode only)
- Supports dynamic addition/removal of SCSI bus segments using the isolation mode
- Does not consume a SCSI ID
- Propagates the RESET/ signal from one side to the other regardless of the SCSI bus state
- Notifies initiator(s) of changes in transmission mode (SE/LVD) on A or B Side segments by using the SCSI bus RESET/
- SCSI Busy LED driver for activity indicator
- Up to four LSI53C180s may be cascaded
- Does not require software
- Supports Double Transition (DT) clocking
- Supports Cyclic Redundancy Check (CRC) in DT data phases
- Supports Domain Validation

### 1.1.3 Specifications

- 40 MHz Input Clock
  - 192-pin Plastic Ball Grid Array package (PBGA). This package is a drop in replacement for the LSI53C140 when the design uses the LSI53C180 pinout.
  - Compliant with the *SCSI Parallel Interface-3 (SPI-3)*
  - Compliant with SCSI Enhanced Parallel Interface (EPI) Specifications
- 

## 1.2 Ultra160 SCSI

The LSI53C180 SCSI Bus Expander supports Ultra160 SCSI. This interface is an extension of the SCSI-3 standards that expands the bandwidth of the SCSI bus to allow faster synchronous data transfers, up to 160 Mbytes/s. Ultra160 SCSI provides a doubling of the data rate over the Ultra2 SCSI interface. All new speeds after Ultra2 are wide.

### 1.2.1 Double Transition (DT) Clocking

Ultra160 provides DT clocking for LVD transfers where clocking is defined on the rising and falling edges of the clock. The latching of data on both the assertion edge and the negation edge of the REQ/ACK signal represents DT data phases. DT data phase encompasses both the DT Data In and the DT Data Out phase. DT data phases use only 16-bit, synchronous transfers.

Information unit and data group transfers use DT data phases to transfer data. Information unit transfers transmit all nexus, task management, task attribute, command, data, and protection. Data group transfers transmit all data and protection. The number of bytes transferred for an information unit or data group is always a multiple of four. Refer to the *SCSI Parallel Interface-3 (SPI-3)* for more detailed information about DT clocking.

### 1.2.2 Cyclic Redundancy Check (CRC)

Ultra160 supports CRC, which represents error checking code to detect the validity of data. CRC increases the reliability of data transfers since four bytes of code are transferred along with data. All single bit errors,



two bits in error, or other error types within a single 32-bit range are detected. Refer to SPI-3 to see how CRC generation and transmission occur during data transfers.

### **1.2.3 Domain Validation**

Domain Validation is a procedure that allows a host computer and target SCSI peripheral to negotiate and find the optimal transfer speed. This procedure improves overall reliability of the system by ensuring integrity of the data transferred.

### **1.2.4 Parallel Protocol Request**

Parallel Protocol Request (PPR) messages negotiate a synchronous data transfer agreement, a wide data transfer agreement, and set the protocol options between two SCSI devices. This message exchange negotiates limits about data transmission and establishes an agreement between the two SCSI devices. This agreement applies to ST Data In, ST Data Out, DT Data In, and DT Data Out phases.

For example, a SCSI device could initiate a PPR message whenever it is appropriate to negotiate a data transfer agreement. If the target device is capable of supporting any of the PPR options, it will respond with a PPR message. If not, it responds with a Message Reject message and the two SCSI devices use either SDTR or WDTR messages to negotiate an agreement.

### **1.2.5 Benefits of LVD Link**

The LSI53C180 supports LVD technology for SCSI, a signaling technology that increases the reliability of SCSI data transfers over longer distances than those supported by SE SCSI technology. The low current output of LVD allows the I/O transceivers to be integrated directly onto the chip. LVD provides the reliability of HVD SCSI technology without the added cost of external differential transceivers. LVD allows a longer SCSI cable and more devices on the bus. LVD provides a long-term migration path to even faster SCSI transfer rates without compromising signal integrity, cable length, or connectivity.

For backward compatibility to existing SE devices, the LSI53C180 features multimode LVD Link transceivers that can switch between LVD and SE modes.

Some features of integrated LVD Link multimode transceivers are:

- Supports SE or LVD technology
- Allows greater device connectivity and longer cable length
- LVD Link transceivers save the cost of external differential transceivers
- Supports a long-term performance migration path

# Chapter 2

## Functional Descriptions

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This chapter describes all signals, their groupings, and their functions. It includes these topics:

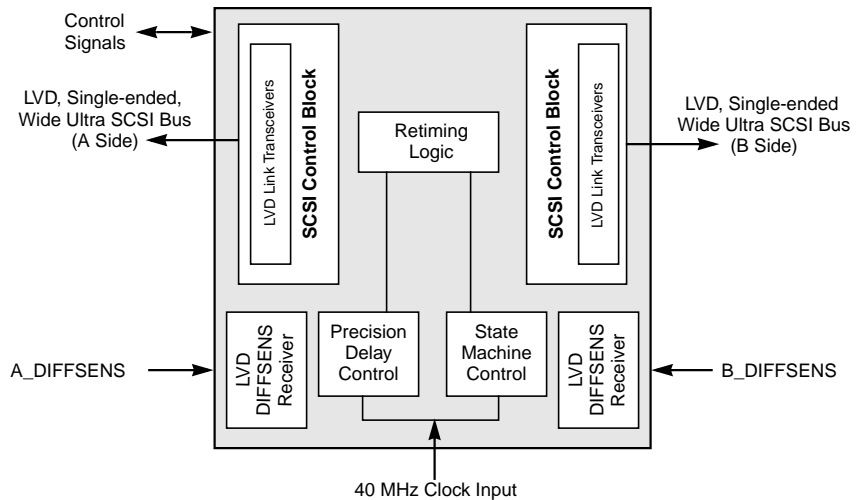
- [Section 2.1, “Interface Signal Descriptions,” page 2-1](#)
  - [Section 2.2, “Internal Control Descriptions,” page 2-14](#)
- 

### 2.1 Interface Signal Descriptions

The LSI53C180 has no programmable registers, and therefore, no software requirements. SCSI control signals control all LSI53C180 functions. [Figure 2.1](#) shows a block diagram of the LSI53C180 device, which is divided into these specific areas:

- A Side SCSI Control Block
  - LVD and SE Drivers and Receivers
- B Side SCSI Control Block
  - LVD and SE Drivers and Receivers
- Retiming Logic
- Precision Delay Control
- State Machine Control

**Figure 2.1 LSI53C180 Block Diagram**



In its simplest form, the LSI53C180 passes data and parity from a source bus to a load bus. The side asserting, deasserting, or releasing the SCSI signals is the source side. The model of the LSI53C180 represents pieces of wire that allow corresponding SCSI signals to flow from one side to the other side. The LSI53C180 monitors arbitration and selection by devices on the bus so it can enable the proper drivers to pass the signals along. In addition, the LSI53C180 does signal retiming to maintain the signal skew budget from the source bus to the load bus.

## 2.1.1 SCSI A Side and B Side Control Blocks

The SCSI A Side pins are connected internally to the corresponding SCSI B Side pins, forming bidirectional connections to the SCSI bus.

In the LVD/LVD mode, the SCSI A Side and B Side control blocks connect to both targets and initiators and accept any asynchronous or synchronous data transfer rates up to the 160 Mbytes/s rate of Wide Ultra160 SCSI. TolerANT<sup>®</sup> and LVD Link technologies are part of both the A Side and B Side control blocks.

### 2.1.1.1 LSI53C180 Requirements for Synchronous Negotiation

The LSI53C180 builds a table of information regarding devices on the bus in on-chip RAM. The PPR, SDTR, and WDTR information for each

device is taken from the MSG bytes during negotiation. For all devices in the configuration to communicate accurately through the LSI53C180 at Ultra160 (Fast-80) rates, it is necessary for a complete synchronous negotiation to take place between the initiator and target(s) prior to any data transfer. On a 16-bit bus, the LSI53C180 at Ultra160 approaches rates of 160 Mbytes/s. The LSI53C180 defaults to Fast-20 rates when a valid negotiation between the initiator and target has not occurred.

### **2.1.1.2 TolerANT Technology**

In SE mode, the LSI53C180 features TolerANT technology, which includes active negation on the SCSI drivers and input signal filtering on the SCSI receivers. Active negation causes the SCSI Request, Acknowledge, Data, and Parity signals to be actively driven HIGH rather than passively pulled up by terminators.

TolerANT receiver technology improves data integrity in unreliable cabling environments, where other devices would be subject to data corruption. TolerANT receivers filter the SCSI bus signals to eliminate unwanted transitions without the long signal delays associated with RC-type input filters. This improved driver and receiver technology helps eliminate double clocking of data, the single biggest reliability issue with SCSI operations.

The benefits of TolerANT technology include increased immunity to noise on the deasserting signal edge, better performance due to balanced duty cycles, and improved SCSI transfer rates. In addition, TolerANT SCSI devices prevent glitches on the SCSI bus at power-up or power-down, so other devices on the bus are also protected from data corruption.

### **2.1.1.3 LVD Link Technology**

To support greater device connectivity and longer SCSI cables, the LSI53C180 features LVD Link technology, the LSI Logic implementation of multimode LVD SCSI. LVD Link transceivers provide the inherent reliability of differential SCSI, and a long-term migration path of faster SCSI transfer rates.

LVD Link technology is based on current drive. Its low output current reduces the power needed to drive the SCSI bus. Therefore, the I/O drivers can be integrated directly onto the chip. This reduces the cost and complexity compared to traditional (high power) differential designs.

LVD Link lowers the amplitude of noise reflections and allows higher transmission frequencies.

The LVD Link transceivers in Side A and Side B operate in the LVD or SE modes. The LSI53C180 automatically detects the type of signal connected, based on the voltages detected by A\_DIFFSENS and B\_DIFFSENS.

### **2.1.2 Retiming Logic**

The SCSI signals, as they propagate from one side of the LSI53C180 to the other side, are processed by logic circuits that retime the bus signals, as needed, to guarantee or improve the required SCSI timings. The retiming logic is governed by the State Machine Controls that keep track of SCSI phases, the location of initiator and target devices, and various timing functions. In addition, the retiming logic contains numerous delay elements that are periodically calibrated by the Precision Delay Control block in order to guarantee specified timing such as output pulse widths, setup and hold times, and other elements.

When a synchronous negotiation takes place between devices, a nexus is formed, and the corresponding information on that nexus is stored in the on-chip RAM. This information remains in place until a chip reset, power down, or renegotiation occurs. This enables the chip to make more accurate retiming adjustments.

### **2.1.3 Precision Delay Control**

The Precision Delay Control block provides calibration information to the precision delay elements in the Retiming Logic block. This calibration information provides precise timing as signals propagate through the device. As the LSI53C180 voltage and temperature vary over time, the Precision Delay Control block periodically updates the delay settings in the Retiming Logic. The purpose of these updates is to maintain constant and precise control over bus timing.

### **2.1.4 State Machine Control**

The State Machine Control tracks the SCSI bus phase protocol and other internal operating conditions. This block provides signals to the Retiming Logic that identify how to properly handle SCSI bus signal retiming based on SCSI protocol.

## 2.1.5 DIFFSENS Receiver

The LSI53C180 contains LVD DIFFSENS receivers that detect the voltage level on the A Side or B Side DIFFSENS lines to inform the LSI53C180 of the transmission mode being used by the SCSI buses. A device does not change its present signal driver or receiver mode based on the DIFFSENS voltage levels unless a new mode is sensed continuously for at least 100 ms.

Transmission mode detection for SE or LVD is accomplished through the use of the DIFFSENS lines. [Table 2.1](#) shows the voltages on the DIFFSENS lines and modes they will cause.

**Table 2.1 DIFFSENS Voltage Levels**

Voltage	Mode
-0.35 to +0.5	SE
+0.7 to +1.9	LVD

## 2.1.6 Dynamic Transmission Mode Changes

Any dynamic mode change (SE/LVD) on a bus segment is considered to be a significant event that requires the initiator to determine whether the mode change meets the requirements for that bus segment.

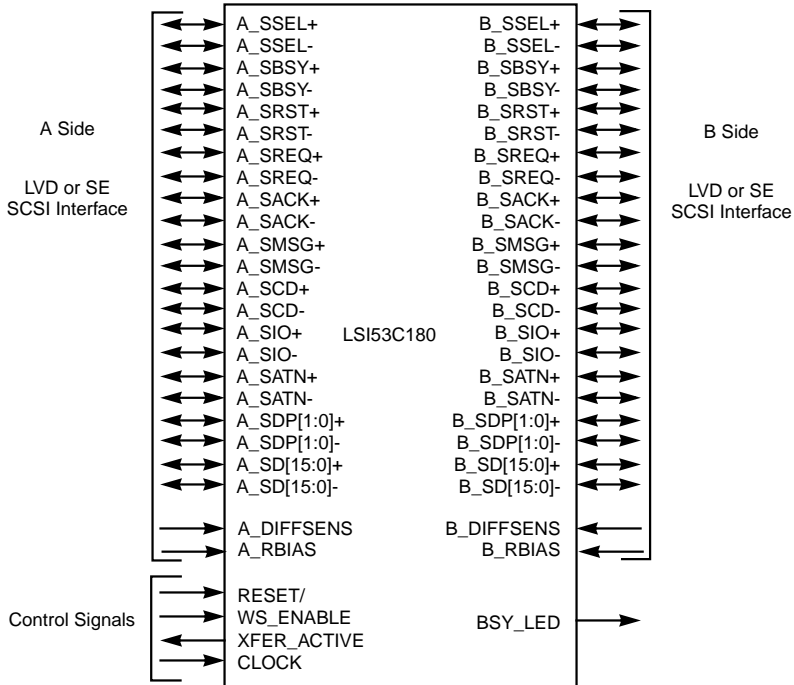
The LSI53C180 supports dynamic transmission mode changes by notifying the initiator(s) of changes in transmission mode (SE/LVD) on A or B Side segments by using the SCSI bus RESET. The DIFFSENS line detects a valid mode switch on the bus segments. After the DIFFSENS state is present for 100 ms, the LSI53C180 generates a SCSI reset on the opposite bus from the one that the transmission mode change occurred on. This reset informs any initiators residing on the opposite segment about the change in the transmission mode. The initiator(s) then renegotiates synchronous transfer rates with each device on that segment.

## 2.1.7 SCSI Signal Descriptions

For a description of a specific signal, see [Section 3.1, “Signal Descriptions,”](#) in [Chapter 3](#). For signal electrical characteristics, see [Section 3.2, “Electrical Characteristics.”](#) For SCSI bus signal timing, see

Section 3.2.4, “SCSI Interface Timing.” Figure 2.2 shows the LSI53C180 signal grouping. A description of the signal groups follows.

**Figure 2.2 LSI53C180 Signal Grouping**



### 2.1.7.1 Data and Parity (SD and SDP)

The signals named A\_SD[15:0] and A\_SDP[1:0] are the data and parity signals from the A Side, and B\_SD[15:0] and B\_SDP[1:0] are the data and parity signals from the B Side of the LSI53C180. These signals are sent and received from the LSI53C180 by using SCSI compatible drivers and receiver logic designed into the LSI53C180 interfaces. This logic provides the multimode LVD and SE interfaces in the chip. This logic also provides the necessary drive, sense thresholds, and input hysteresis to function correctly in a SCSI bus environment.

The LSI53C180 receives data and parity signals and passes them from the source bus to the load bus and provides any necessary edge shifting to guarantee the skew budget for the load bus. Either side of the LSI53C180 may be the source bus or the load bus. The side that is



asserting, deasserting, or releasing the SCSI signals is the source side. These steps describe the LSI53C180 data processing:

1. Asserted data is accepted by the receiver logic as soon as it is received. Once the clock signal (REQ/ACK) has been received, data is gated from the receiver latch.
2. The path is next tested to ensure the signal if being driven by the LSI53C180 is not misinterpreted as an incoming signal.
3. The data is then leading edge filtered. The assertion edge is held for a specified time to prevent any signal bounce. The duration is controlled by the input signal.
4. The next stage uses a latch to sample the signal. This provides a stable data window for the load bus.
5. The final step develops pull-up and pull-down controls for the SCSI I/O logic, including 3-state controls for the pull-up.
6. A parallel function ensures that bus (transmission line) recovery occurs for a specified time after the last signal deassertion on each signal line.

#### **2.1.7.2 SCSI Bus Activity LED (BSY\_LED)**

Internal logic detects SCSI bus activity and generates a signal that produces an active HIGH output. This output can be used to drive a LED to indicate SCSI activity.

The internal circuitry is a digital one shot that is an active HIGH with a minimum pulse width of 16 ms. The BSY\_LED output current is 8 mA. This output may have an LED attached to it with the other lead of the LED grounded through a suitable resistor.

#### **2.1.7.3 Select Control (SSEL)**

A\_SSEL and B\_SSEL are control signals used during bus arbitration and selection. Whichever side asserts, SSEL propagates it to the other side. If both signals are asserted at the same time, the A Side receives SSEL and sends it to the B Side. This output has pull-down control for an open collector driver. The processing steps for the signals are:

1. The input signal is blocked if it is being driven by the LSI53C180.
2. The next stage is a leading edge filter. This ensures that the output does not switch for a specified time after the leading edge. The duration of the input signal then determines the duration of the output.
3. A parallel function ensures that bus (transmission line) recovery occurs for a specified time after the last signal deassertion on each signal line.

#### **2.1.7.4 Busy Control (SBSY)**

A\_SBSY and B\_SBSY signals are propagated from the source bus to the load bus. The busy control signals go through this process:

1. The bus is tested to ensure the signal if being driven by the LSI53C180 is not misinterpreted as an incoming signal.
2. The data is then leading edge filtered. The assertion edge is held for a specified time to prevent any signal bounce. The input signal controls the duration.
3. The signal path switches the long and short filters used in the circuit depending upon the current state of the LSI53C180. The current state of the LSI53C180 State Machine that tracks SCSI phases selects the mode. The short filter mode passes data through, while the long filter mode indicates the bus free state. When the Busy (SBSY) and Select (SSEL) sources switch from side to side, the long filter mode is used. This output is then fed to the output driver, which is a pull-down open collector only.
4. A parallel function ensures that bus (transmission line) recovery is available for a specified time after the last signal deassertion on each signal line.

#### **2.1.7.5 Reset Control (SRST)**

A\_SRST and B\_SRST are also passed from the source to the load bus. This output has pull-down control for an open collector driver. The reset signals are processed in this sequence:

1. The input signal is blocked if it is already being driven by the LSI53C180.

2. The next stage is a leading edge filter. This ensures that the output will not switch during a specified time after the leading edge. The duration of the input signal then determines the duration of the output.
3. A parallel function ensures that bus (transmission line) recovery occurs for a specified time after the last signal deassertion on each signal line.

When the LSI53C180 senses a true mode change on either bus, it generates a SCSI reset to the opposite bus. For example, when LVD mode changes to SE mode, a reset occurs.

#### **2.1.7.6 Request and Acknowledge Control (SREQ and SACK)**

A\_SREQ, A\_SACK, B\_SREQ, and B\_SACK are clock and control signals. Their signal paths contain controls to guarantee minimum pulse widths, filter edges, and do some retiming when used as data transfer clocks. In DT clocking, both leading and trailing edges are filtered, while only the leading edge is filtered in single transition clocking. SREQ and SACK have paths from the A Side to the B Side and from the B Side to the A Side. The received signal goes through these processing steps before being sent to the opposite bus:

1. The asserted input signal is sensed and forwarded to the next stage if the direction control permits it. The direction controls are developed from state machines that are driven by the sequence of bus control signals.
2. The signal must then pass the test of **not** being regenerated by the LSI53C180.
3. The next stage is a leading edge filter. This ensures that the output does not switch during the specified hold time after the leading edge. The duration of the input signal determines the duration of the output after the hold time. The circuit guarantees a minimum pulse rate.
4. The next stage passes the signal if it is not a data clock. If SREQ or SACK is a data clock, it delays the leading edge to improve data output setup times. The input signal again controls the duration.
5. This stage is a trailing edge signal filter. When the signal deasserts, the filter does not permit any signal bounce. The output signal deasserts at the first deasserted edge of the input signal.

6. The last stage develops pull-up and pull-down signals with drive and 3-state control.
7. A parallel function ensures that bus (transmission line) recovery occurs for a specified time after the last signal deassertion on each signal line.

#### **2.1.7.7 Control/Data, Input/Output, Message, and Attention Controls (SCD, SIO, SMSG, and SATN)**

A\_SCD, A\_SIO, A\_SMSG, A\_SATN, B\_SCD, B\_SIO, B\_SMSG, and B\_SATN are control signals that have the following processing steps:

1. The input signal is blocked if it is being driven by the LSI53C180.
2. The next stage is a leading edge filter. This ensures the output does not switch for a specified time after the leading edge. The duration of the input signal determines the duration of the output.
3. The final stage develops pull-up and pull-down controls for the SCSI I/O logic, including 3-state controls for the pull-up.
4. A parallel function ensures that bus (transmission line) recovery is for a specified time after the last signal deassertion on each signal line.

#### **2.1.7.8 Multimode Signal Control**

A\_SD[15:0], A\_SDP[1:0], A\_SBSY, A\_SSEL, A\_SCD, A\_SIO, A\_SMSG, A\_SREQ, A\_SACK, A\_SATN, A\_SRST, B\_SD[15:0], B\_SDP[1:0], B\_SBSY, B\_SSEL, B\_SCD, B\_SIO, B\_SMSG, B\_SREQ, B\_SACK, B\_SATN, and B\_SRST are all multimode signals. The mode is controlled by the voltage sensed at the DIFFSENS input. The A and B Sides are independently controlled.

When the correct DIFFSENS voltage selects SE mode, the plus signal leads are internally tied to ground and the minus SCSI signals are the SE input/outputs.

When the correct DIFFSENS voltage selects LVD mode, the plus and minus signal leads are the differential signal pairs.

A transition from any mode to another mode causes a SCSI RST to be asserted on the opposite SCSI bus as a notification of state change.

### 2.1.7.9 A and B Differential Sense (A\_DIFFSENS and B\_DIFFSENS)

These control pins determine the mode of SCSI bus signaling that will be expected.

**Table 2.2 Mode Sense Control Voltage Levels**

Voltage	Mode
-0.35 to +0.5	SE
+0.7 to +1.9	LVD

For example, if a differential source is plugged into the B Side that has been configured to run in the differential mode and if a SE source is detected, then the B Side is disabled and no B Side signals are driven. This protection mechanism is for SE interfaces that are connected to differential drivers.

### 2.1.7.10 A and B RBIAS (LVD Current Control)

These control pins require a 10 K 1% resistor connected to  $V_{DD}$ .

## 2.1.8 Control Signals

This section provides information about the RESET/, WS\_ENABLE, and XFER\_ACTIVE pins. It also describes the function of the CLOCK input.

### 2.1.8.1 Chip Reset (RESET/)

This general purpose chip reset forces all of the internal elements of the LSI53C180 into a known state. It brings the State Machine to an idle state and forces all controls to a passive state. The minimum RESET/ input asserted pulse width is 100 ns.

The LSI53C180 also contains an internal Power On Reset (POR) function that is ORed with the chip reset pin. This eliminates the need

for an external chip reset if the power supply meets ramp up specifications.

**Table 2.3 RESET/ Control Signal Polarity**

Signal Level	State	Effect
LOW = 0	Asserted	Reset is forced to all internal LSI53C180 elements.
HIGH = 1	Deasserted	LSI53C180 is not in a forced reset state.

### 2.1.8.2 Warm Swap Enable (WS\_ENABLE/)

This input removes the chip from an active bus without disturbing the current SCSI transaction (for Warm Swap). When the WS\_ENABLE/ pin is asserted, after detection of the next bus free state, the SCSI signals are 3-stated. This occurs so that the LSI53C180 no longer passes through signals until the WS\_ENABLE/ pin is deasserted HIGH and both SCSI buses enter the Bus Free state. As an indication that the chip is idle, or ready to be warm swapped, the XFER\_ACTIVE signal deasserts LOW. An LED or some other indicator could be connected to the XFER\_ACTIVE signal. To isolate buses in certain situations, use this Warm Swap Enable feature.

**Table 2.4 WS\_ENABLE/ Signal Polarity**

Signal Level	State	Effect
LOW = 0	Asserted	The LSI53C180 is requested to go off-line after detection of a SCSI Bus Free state.
HIGH = 1	Deasserted	The LSI53C180 is enabled to run normally.

### 2.1.8.3 Transfer Active (XFER\_ACTIVE)

This output is an indication that the chip has finished its internal testing, the SCSI bus has entered a Bus Free state, and SCSI traffic can now

pass from one bus to the other. The signal is asserted HIGH when the chip is active.

**Table 2.5 XFER\_ACTIVE Signal Polarity**

Signal Level	State	Effect
HIGH = 1	Asserted	Indicates normal operation, and transfers through the LSI53C180 are enabled.
LOW = 0	Deasserted	The LSI53C180 has detected a Bus Free state due to WS_ENABLE being LOW, thus disabling transfers through the device.

#### 2.1.8.4 Clock (CLOCK)

This is the 40 MHz oscillator input to the LSI53C180. It is the clock source for the protocol control state machines and timing generation logic. This clock is not used in any bus signal transfer paths.

#### 2.1.9 SCSI Termination

The terminator networks provide the biasing needed to pull signals to an inactive voltage level, and to match the impedance seen at the end of the cable with the characteristic impedance of the cable. Terminators must be installed at the extreme ends of each SCSI segment, and only at the ends. No SCSI segment should ever have more or less than two terminators installed and active. SCSI host adapters should provide a means of accommodating terminators. The terminators should be socketed, so they may be removed if not needed. Otherwise, the terminators should be disabled by software means.

Multimode terminators are required because they provide both LVD and SE termination, depending on what mode of operation is detected by the DIFFSENS pins.

Important: LSI Logic recommends that active termination be used for the bus connections to the LSI53C180. The Unitrode 5630 or Dallas 2108 commonly used for Ultra2 buses can also be used interchangeably for Ultra160. The Unitrode 5628 can be used for Ultra160 and allows use of two devices on the SCSI bus rather than three.

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## 2.2 Internal Control Descriptions

This section provides information about self-calibration, delay line structures, and busy filters.

### 2.2.1 Self-Calibration

The LSI53C180 contains internal logic that adjusts the internal timing based on analyzing the time through a long asynchronous inverter logic chain versus a synchronous counter. The timing functions use the resulting self-calibration value to adjust to their nominal values based on the performance of this circuit.

The LSI53C180 has 24 critical timing chains and each has its own calibration circuit and stored calibration value. The counter logic is replicated four times so four calibrations can occur in parallel. This allows the 24 calibration values to be updated by six calibration cycles.

Self-calibration is triggered every 8.1 seconds to account for temperature and voltage changes.

### 2.2.2 Delay Line Structures

Some fixed delay functions are required within the signal and control interfaces from bus to bus. The LSI53C180 uses programmable delay lines to implement delays. The incremental points in the chain are selected by multiplexers. Self-calibration takes care of process, temperature, and voltage effects.

#### 2.2.2.1 Data Path

The data path through the LSI53C180 includes two levels of latches. One latch is in the receiver and the input clock, REQ or ACK, generates the hold. This level captures the data that may have minimal setup and hold. A second latch occurs to hold the data in order to transmit optimal signals on the isolated bus. This level provides maximum setup and hold along with a regenerated clock. The data path also provides a timer for each data bit that protects reception from a target bus for a nominal 30 ns after the driver is deasserted.



### **2.2.2.2 REQ/ACK**

These input clock signals get edge filtered and stretched to minimum values to avoid glitches. In DT clocking, both leading and trailing edges are filtered, while only the leading edge is filtered in single transition clocking. These filters provide edge filtering to remove noise within the initial signal transition. The current transmission speed selects the time values.

### **2.2.3 Busy Filters**

The busy control signal passes from source to load bus with filtering selected by the current state of the SCSI bus. This filter provides a synchronized leading edge signal that is not true until the input signal has been stable. The trailing edge occurs within several nanoseconds of the input being deasserted. When the BSY signal is asserted before and after the SEL signal, the filter is on.



# Chapter 3

## Specifications

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This chapter provides the pin descriptions associated with the LSI53C180 as well as electrical characteristics. It includes these topics:

- [Section 3.1, “Signal Descriptions,” page 3-1](#)
  - [Section 3.2, “Electrical Characteristics,” page 3-7](#)
  - [Section 3.3, “Mechanical Drawings,” page 3-20](#)
- 

### 3.1 Signal Descriptions

The LSI53C180 is packaged in a 192-pin Ball Grid Array (BGA) shown in [Figure 3.1](#) and [Figure 3.2](#). The LSI53C180 signal grouping is shown in [Figure 3.3](#). Tables [3.1](#) through [3.4](#) list the signal descriptions grouped by function:

- [SCSI A Side Interface Pins \(Table 3.1\)](#)
- [SCSI B Side Interface Pins \(Table 3.2\)](#)
- [Chip Interface Control Pins \(Table 3.3\)](#)
- [Power and Ground Pins \(Table 3.4\)](#)

[Figure 3.1](#) and [Figure 3.2](#) display the left and right halves of the LSI53C180 192-pin BGA top view.

**Figure 3.1 Left Half of LSI53C180 192-Pin BGA Top View**

A1 NC	A2 VDD <sub>IO</sub>	A3 NC	A4 NC	A5 NC	A6 XFER_ACTIVE	A7 RESET/	A8 A_DIFFSENS	A9 A_SD12-	
B1 B_SD11+	B2 B_SD11-	B3 NC	B4 NC	B5 WS_ENABLE/	B6 BSY_LED	B7 NC	B8 VDD <sub>CORE</sub>	B9 A_SD12+	
C1 B_SD10+	C2 B_SD10-	C3 B_DIFFSENS	C4 NC	C5 VDD <sub>SCSI</sub>	C6 NC	C7 VSS	C8 CLOCK	C9 VDD <sub>SCSI</sub>	
D1 B_SD9+	D2 B_SD9-	D3 NC							
E1 B_SD8+	E2 B_SD8-	E3 VDD <sub>SCSI</sub>							
F1 B_SIO+	F2 B_SIO-	F3 NC							
G1 B_SREQ+	G2 B_SREQ-	G3 VSS							
H1 B_SCD-	H2 B_SSEL+	H3 B_SCD+							
J1 B_SSEL-	J2 B_SMSG+	J3 VDD <sub>SCSI</sub>							
K1 B_SMSG-	K2 B_SRST+	K3 VDD <sub>CORE</sub>							
L1 B_SRST-	L2 NC	L3 VSS							
M1 B_SACK+	M2 B_SACK-	M3 B_SBSY+							
N1 B_SBSY-	N2 B_SATN+	N3 VDD <sub>SCSI</sub>							
P1 B_SATN-	P2 B_SDP0-	P3 B_SDP0+							
R1 B_RBIAS	R2 B_SD7+	R3 B_SD7-							R4 NC
T1 NC	T2 B_SD6+	T3 B_SD5+	T4 B_SD4+	T5 B_SD3+	T6 B_SD2-	T7 B_SD1+	T8 B_SD0+	T9 B_SDP1+	
U1 NC	U2 B_SD6-	U3 B_SD5-	U4 B_SD4-	U5 B_SD3-	U6 NC	U7 B_SD1-	U8 VDD <sub>CORE</sub>	U9 B_SDP1-	
							G7 VSS	G8 VSS	G9 VSS
							H7 VSS	H8 VSS	H9 VSS
							J7 VSS	J8 VSS	
							K7 VSS	K8 VSS	K9 VSS
							L7 VSS	L8 VSS	L9 VSS

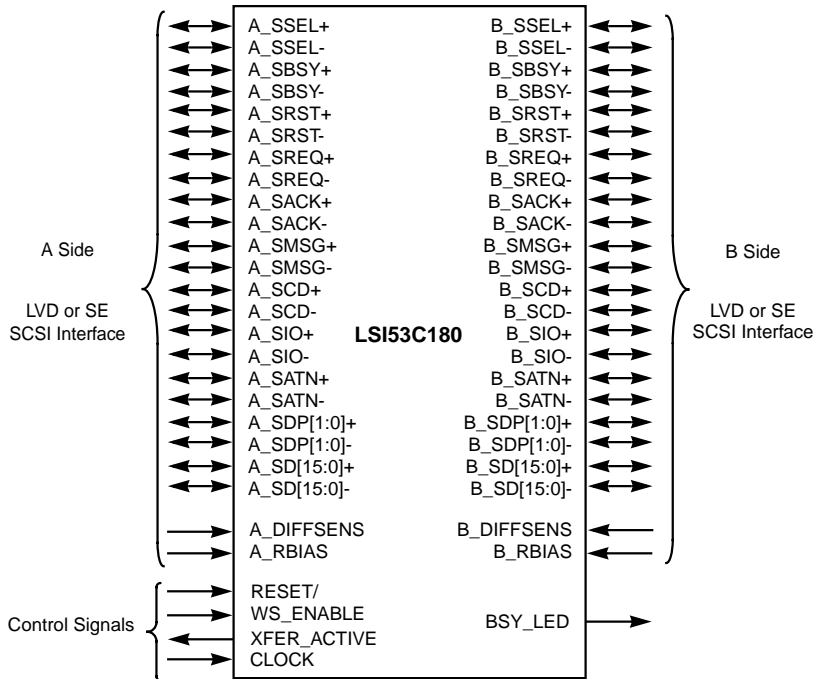
**Figure 3.2 Right Half of LSI53C180 192-Pin BGA Top View**

A10	A11	A12	A13	A14	A15	A16	A17
A_SD13-	A_SD14+	A_SD15+	A_SD0-	A_SD1-	A_SD2-	A_SD3-	NC
B10	B11	B12	B13	B14	B15	B16	B17
A_SD14-	A_SD15-	A_SDP1-	A_SD0+	A_SD1+	A_SD2+	A_SD3+	A_SD4-
C10	C11	C12	C13	C14	C15	C16	C17
A_SD13+	VSS	A_SDP1+	VDD <sub>scSI</sub>	NC	NC	A_SD5-	A_SD4+
					D15	D16	D17
					A_SD5+	A_SD6+	A_SD6-
					E15	E16	E17
					VDD <sub>scSI</sub>	A_SD7+	A_SD7-
					F15	F16	F17
					NC	A_SDP0+	A_SDP0-
					G15	G16	G17
					VSS	A_SATN+	A_SATN-
					H15	H16	H17
					NC	A_SBSY+	A_SBSY-
					J15	J16	J17
					VDD	A_SACK+	A_SACK-
					K15	K16	K17
					VDD <sub>CORE</sub>	A_SRST-	A_RBIAS
					L15	L16	L17
					VSS	A_SMSG-	A_SRST+
					M15	M16	M17
					A_SSEL+	A_SSEL-	A_SMSG+
					N15	N16	N17
					VDD <sub>scSI</sub>	A_SCD+	A_SCD-
					P15	P16	P17
					NC	A_SREQ+	A_SREQ-
R10	R11	R12	R13	R14	R15	R16	R17
NC	VSS	NC	VDD <sub>scSI</sub>	A_SD10+	A_SD9-	A_SIO+	A_SIO-
T10	T11	T12	T13	T14	T15	T16	T17
B_SD15+	B_SD14+	B_SD13+	B_SD12+	A_SD11+	A_SD10-	A_SD8+	A_SD8-
U10	U11	U12	U13	U14	U15	U16	U17
B_SD15-	B_SD14-	B_SD13-	B_SD12-	A_SD11-	A_SD9+	NC	NC

G10	G11
VSS	VSS
H10	H11
VSS	VSS
J10	J11
VSS	VSS
K10	K11
VSS	VSS
L10	L11
VSS	VSS

**Figure 3.3 LSI53C180 Functional Signal Grouping**



**Table 3.1 SCSI A Side Interface Pins**

<b>SCSI A</b>	<b>BGA Pin</b>	<b>Type</b>	<b>Description</b>
A_SSEL+,-	M15, M16	I/O	A Side SCSI bus Select control signal.
A_SBSY+,-	H16, H17	I/O	A Side SCSI bus Busy control signal.
A_SRST+,-	L17, K16	I/O	A Side SCSI bus Reset control signal.
A_SREQ+,-	P16, P17	I/O	A Side SCSI bus Request control signal.
A_SACK+,-	J16, J17	I/O	A Side SCSI bus Acknowledge control signal.
A_SMSG+,-	M17, L16	I/O	A Side SCSI bus Message control signal.
A_SCD+,-	N16, N17	I/O	A Side SCSI bus Control and Data control signal.
A_SIO+,-	R16, R17	I/O	A Side SCSI bus Input and Output control signal.
A_SATN+,-	G16, G17	I/O	A Side SCSI bus Attention control signal.
A_SDP[1:0]+,-	C12, B12, F16, F17	I/O	A Side SCSI bus Data Parity signal.
A_SD[15:0]+,-	A12, B11, A11, B10, C10, A10, B9, A9, T14, U14, R14, T15, U15, R15, T16, T17, E16, E17, D16, D17, D15, C16, C17, B17, B16, A16, B15, A15, B14, A14, B13, A13	I/O	A Side SCSI bus Data signals.
A_DIFFSENS	A8	I	A Side SCSI bus Differential Sense signal.
A_RBIAS	K17	RBIAS	LVD current control.

**Table 3.2 SCSI B Side Interface Pins**

SCSI B	Pin	Type	Description
B_SSEL+,-	H2, J1	I/O	B Side SCSI bus Select control signal.
B_SBSY+,-	M3, N1	I/O	B Side SCSI bus Busy control signal.
B_SRST+,-	K2, L1	I/O	B Side SCSI bus Reset control signal.
B_SREQ+,-	G1, G2	I/O	B Side SCSI bus Request control signal.
B_SACK+,-	M1, M2	I/O	B Side SCSI bus Acknowledge control signal.
B_SMSG+,-	J2, K1	I/O	B Side SCSI bus Message control signal.
B_SCD+,-	H3, H1	I/O	B Side SCSI bus Control and Data control signal.
B_SIO+,-	F1, F2	I/O	B Side SCSI bus Input and Output control signal.
B_SATN+,-	N2, P1	I/O	B Side SCSI bus Attention control signal.
B_SDP[1:0]+,-	T9, U9, P3, P2	I/O	B Side SCSI bus Data Parity signal.
B_SD[15:0]+,-	T10, U10, T11, U11, T12, U12, T13, U13, B1, B2, C1, C2, D1, D2, E1, E2, R2, R3, T2, U2, T3, U3, T4, U4, T5, U5, R6, T6, T7, U7, T8, R8	I/O	B Side SCSI bus Data signals.
B_DIFFSENS	C3	I	B Side SCSI bus Differential Sense signal.
B_RBIAS	R1	RBIAS	LVD current control.

**Table 3.3 Chip Interface Control Pins**

Control	Pin	Type	Description
RESET/	A7	I	Master Reset for LSI53C180, active LOW.
WS_ENABLE/	B5	I	Enable/disable SCSI transfers through the LSI53C180.
XFER_ACTIVE	A6	O	Transfers through the LSI53C180 are enabled/disabled.
CLOCK	C8	I	Oscillator input for LSI53C180 (40 MHz).
BSY_LED	B6	O	SCSI activity LED output, 8 mA.



**Table 3.4 Power and Ground Pins**

Power and Ground	Pin	Type	Description
VDD <sub>SCSI</sub>	C5, C9, C13, E3, E15, J3, J15, N3, N15, R5, R9, R13	I	Power supplies to the SCSI bus I/O pins.
VDD <sub>CORE</sub>	B8, K3, K15, U8	I	Power supplies to the CORE logic.
VDD <sub>IO</sub>	A2	I	Power supplies to the I/O logic.
VSS	C7, C11, G3, G7, G8, G9, G10, G11, G15, H7, H8, H9, H10, H11, J7, J8, J10, J11, K7, K8, K9, K10, K11, L3, L7, L8, L9, L10, L11, L15, R7, R11	I	Ground ring.
NC	A1, A3, A4, A5, A17, B3, B4, B7, C4, C6, C14, C15, D3, F3, F15, H15, L2, P15, R4, R10, R12, T1, U1, U6, U16, U17	N/A	No Connections.

**Note:**

- All V<sub>DD</sub> pins must be supplied 3.3 V. The LSI53C180 output signals drive 3.3 V.
- If the power supplies to the VDD<sub>IO</sub> and VDD<sub>CORE</sub> pins in a chip testing environment are separated, either power up the pins simultaneously or power up VDD<sub>CORE</sub> before VDD<sub>IO</sub>. The VDD<sub>IO</sub> pin must always power down before the VDD<sub>CORE</sub> pin.

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## 3.2 Electrical Characteristics

This section specifies the DC and AC electrical characteristics of the LSI53C180. These electrical characteristics are listed in four categories:

- [DC Characteristics](#)
- [TolerANT Technology Electrical Characteristics](#)
- [AC Characteristics](#)
- [SCSI Interface Timing](#)

### 3.2.1 DC Characteristics

**Table 3.5 Absolute Maximum Stress Ratings<sup>1</sup>**

Symbol	Parameter	Min	Max	Units	Test Conditions
T <sub>STG</sub>	Storage temperature	-55	150	°C	–
V <sub>DD</sub>	Supply voltage	-0.5	4.5	V	–
V <sub>IN</sub>	Input Voltage	V <sub>SS</sub> -0.3	V <sub>DD</sub> +0.3	V	–
V <sub>IN5V</sub>	Input Voltage (5 V TolerANT pins)	V <sub>SS</sub> -0.3	5.25	V	–
I <sub>LP</sub> <sup>2</sup>	Latch-up current	±150	–	mA	–
ESD	Electrostatic discharge	–	2 K	V	MIL-STD 883C, Method 3015.7

1. Stresses beyond those listed above may cause permanent damage to the device. These are stress ratings only; functional operation of the device at these or any other conditions beyond those indicated in the Operating Conditions section of the manual is not implied.
2. -2 V < V<sub>PIN</sub> < 8 V.

**Table 3.6 Operating Conditions<sup>1</sup>**

Symbol	Parameter	Min	Max	Units	Test Conditions
V <sub>DD</sub>	Supply voltage	3.13	3.47	V	–
I <sub>DD</sub>	SE Mode Supply <sup>2</sup> Current (dynamic)	–	200	mA	–
I <sub>DD-I/O</sub>	LVD Mode Supply Current (dynamic)	–	600	mA	–
I <sub>DD</sub>	Supply current (static)	–	1	mA	–
T <sub>A</sub>	Operating free air	0	70	°C	–
θ <sub>JA</sub>	Thermal resistance (junction to ambient air)	–	35	°C/W	–

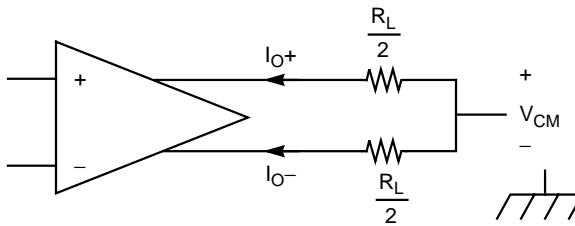
1. Conditions that exceed the operating limits may cause the device to function incorrectly.
2. Core and analog supply only.

**Table 3.7 LVD Driver SCSI Signals—B\_SD[15:0] $\pm$ , B\_SDP[1:0] $\pm$ , B\_SCD $\pm$ , B\_SIO $\pm$ , B\_SMSG $\pm$ , B\_SREQ $\pm$ , B\_SACK $\pm$ , B\_SBSY $\pm$ , B\_SATN $\pm$ , B\_SSEL $\pm$ , B\_SRST $\pm$ <sup>1</sup>**

Symbol	Parameter	Min	Max	Units	Test Conditions
$I_{O+}$	Source (+) current	9.6	14.4	mA	Asserted state
$I_{O-}$	Sink (-) current	-9.6	-14.4	mA	Asserted state
$I_{O+}$	Source (+) current	-6.4	-9.6	mA	Negated state
$I_{O-}$	Sink (-) current	6.4	9.6	mA	Negated state
$I_{OZ}$	3-state leakage	-20	20	$\mu$ A	$V_{PIN} = 0$ V, 3.47 V

1.  $V_{CM} = 0.7 - 1.8$  V,  $R_L = 0 - 110 \Omega$ ,  $R_{bias} = 10$  k $\Omega$ .

**Figure 3.4 LVD Driver**

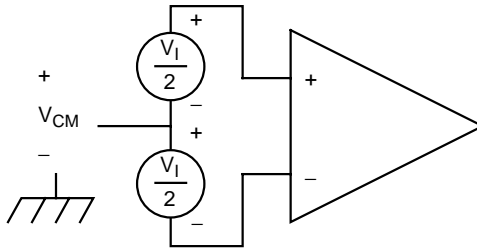


**Table 3.8 LVD Receiver SCSI Signals—B\_SD[15:0] $\pm$ , B\_SDP[1:0] $\pm$ , B\_SCD $\pm$ , B\_SIO $\pm$ , B\_SMSG $\pm$ , B\_SREQ $\pm$ , B\_SACK $\pm$ , B\_SBSY $\pm$ , B\_SATN $\pm$ , B\_SSEL $\pm$ , B\_SRST $\pm$ <sup>1</sup>**

Symbol	Parameter	Min	Max	Units	Test Conditions
$V_I$	LVD receiver voltage asserting	60	-	mV	-
$V_I$	LVD receiver voltage negating	-	-60	mV	-

1.  $V_{CM} = 0.7 - 1.8$  V.

**Figure 3.5 LVD Receiver**



**Table 3.9 DIFFSENS SCSI Signal**

Symbol	Parameter	Min	Max	Units	Test Conditions <sup>1</sup>
$V_S$	LVD sense voltage	0.7	1.9	V	Note 1
$V_{IL}$	Single-ended sense voltage	$V_{SS} - 0.3$	0.5	V	Note 1
$I_{OZ}$	3-state leakage	-10	10	$\mu\text{A}$	$V_{PIN} = 0 \text{ V}, 5.25 \text{ V}$

1. Functional test specified for each mode ( $V_S$  and  $V_{IL}$ ).

**Table 3.10 Input Capacitance**

Symbol	Parameter	Min	Max	Units	Test Conditions
$C_I$	Input capacitance of input pads	-	7	pF	-
$C_{IO}$	Input capacitance of I/O pads	-	10	pF	-

**Table 3.11 Bidirectional SCSI Signals—A\_SD[15:0]/, A\_SDP[1:0]/, A\_SREQ/, A\_SACK/, B\_SD[15:0]±, B\_SDP[1:0]±, B\_SREQ±, B\_SACK±**

Symbol	Parameter	Min	Max	Units	Test Conditions
V <sub>IH</sub>	Input high voltage	2.0	V <sub>DD</sub> +0.3	V	–
V <sub>IL</sub>	Input low voltage	V <sub>SS</sub> -0.3	0.8	V	–
V <sub>OH</sub> <sup>1</sup>	Output high voltage	2.0	V <sub>DD</sub>	V	I <sub>OH</sub> = 7.0 mA
V <sub>OL</sub>	Output low voltage	V <sub>SS</sub>	0.5	V	48 mA
I <sub>OZ</sub>	3-state leakage	–20	20	μA	V <sub>PIN</sub> = 0 V, 3.47 V

1. TolerANT active negation enabled.

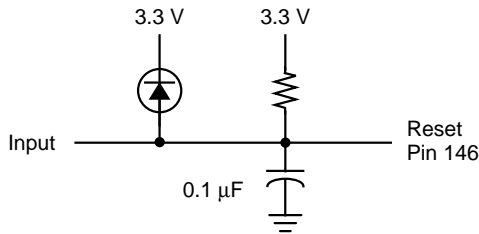
**Table 3.12 Bidirectional SCSI Signals—A\_SCD/, A\_SIO/, A\_SMSG/, A\_SBSY/, A\_SATN/, A\_SSEL/, A\_SRST/, B\_SCD±, B\_SIO±, B\_SMSG±, B\_SBSY±, B\_SATN±, B\_SSEL±, B\_SRST±**

Symbol	Parameter	Min	Max	Units	Test Conditions
V <sub>IH</sub>	Input high voltage	2.0	V <sub>DD</sub> +0.3	V	–
V <sub>IL</sub>	Input low voltage	V <sub>SS</sub> -0.3	0.8	V	–
V <sub>OL</sub>	Output low voltage	V <sub>SS</sub>	0.5	V	48 mA
I <sub>OZ</sub>	3-state leakage	–20	20	μA	V <sub>PIN</sub> = 0 V, 3.47 V

**Table 3.13 Input Control Signals—CLOCK, RESET/, WS\_ENABLE**

Symbol	Parameter	Min	Max	Units	Test Conditions
$V_{IH}$	Input high voltage	2.0	$V_{DD}$	V	–
$V_{IL}$	Input low voltage	$V_{SS} - 0.3$	0.8	V	–
$I_{OZ}$	3-state leakage	–10	10	$\mu A$	$V_{PIN} = 0 V, 5.25 V$

**Figure 3.6 External Reset Circuit**



**Table 3.14 Output Control Signals—BSY\_LED, XFER\_ACTIVE**

Symbol	Parameter	Min	Max	Units	Test Conditions
$V_{OH}$	Output high voltage	2.4	$V_{DD}$	V	8 mA
$V_{OL}$	Output low voltage	$V_{SS}$	0.4	V	8 mA
$I_{OZ}$	3-state leakage	–10	10	$\mu A$	–

## 3.2.2 TolerANT Technology Electrical Characteristics

**Table 3.15 TolerANT Technology Electrical Characteristics<sup>1</sup>**

Symbol	Parameter	Min	Max	Units	Test Conditions
$V_{OH}^2$	Output high voltage	2.0	$V_{DD} + 0.3$	V	$I_{OH} = -7$ mA
$V_{OL}$	Output low voltage	$V_{SS}$	0.5	V	$I_{OL} = 48$ mA
$V_{IH}$	Input high voltage	2.0	$V_{DD} + 0.3$	V	–
$V_{IL}$	Input low voltage	$V_{SS} - 0.3$	0.8	V	Referenced to $V_{SS}$
$V_{IK}$	Input clamp voltage	-0.66	-0.77	V	$V_{DD} = 4.75$ ; $I_I = -20$ mA
$V_{TH}$	Threshold, HIGH to LOW	1.0	1.2	V	–
$V_{TL}$	Threshold, LOW to HIGH	1.4	1.6	V	–
$V_{TH} - V_{TL}$	Hysteresis	300	500	mV	–
$I_{OH}^2$	Output high current	2.5	24	mA	$V_{OH} = 2.5$ V
$I_{OL}$	Output low current	100	200	mA	$V_{OL} = 0.5$ V
$I_{OSH}^2$	Short-circuit output high current	–	625	mA	Output driving low, pin shorted to $V_{DD}$ supply <sup>3</sup>
$I_{OSL}$	Short-circuit output low current	–	95	mA	Output driving high, pin shorted to $V_{SS}$ supply
$I_{LH}$	Input high leakage	–	20	$\mu$ A	$V_{DD} \pm 5\%$ , $V_{PIN} = 2.7$ V
$I_{LL}$	Input low leakage	-20	–	$\mu$ A	$V_{DD} \pm 5\%$ , $V_{PIN} = 0$ V
$I_{PD}$	Power down leakage	–	20		$V_{DD} = 0$ V, $V_{PIN} = 1.2$ V
$R_I$	Input resistance	20	–	M $\Omega$	SCSI pins <sup>4</sup>
$C_P$	Capacitance per pin	–	15	pF	PQFP
$t_R^2$	Rise time, 10% to 90%	4.0	18.5	ns	<a href="#">Figure 3.7</a>

(Sheet 1 of 2)

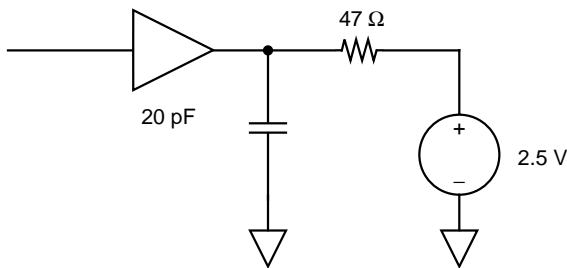
**Table 3.15 TolerANT Technology Electrical Characteristics<sup>1</sup> (Cont.)**

Symbol	Parameter	Min	Max	Units	Test Conditions
$t_F$	Fall time, 90% to 10%	4.0	18.5	ns	<a href="#">Figure 3.7</a>
$dV_H/dt$	Slew rate, LOW to HIGH	0.15	0.50	V/ns	<a href="#">Figure 3.7</a>
$dV_L/dt$	Slew rate, HIGH to LOW	0.15	0.50	V/ns	<a href="#">Figure 3.7</a>
ESD	Electrostatic discharge	2	–	kV	MIL-STD-883C; 3015-7
	Latch-up	100	–	mA	–
	Filter delay	20	30	ns	<a href="#">Figure 3.8</a>
	Ultra filter delay	10	15	ns	<a href="#">Figure 3.8</a>
	Ultra3 filter delay	x	x	ns	<a href="#">Figure 3.8</a>
	Extended filter delay	40	60	ns	<a href="#">Figure 3.8</a>

(Sheet 2 of 2)

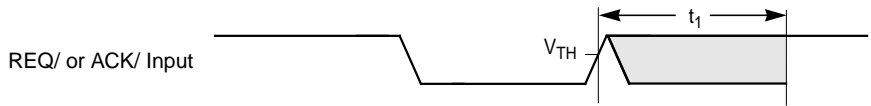
1. These values are guaranteed by periodic characterization; they are not 100% tested on every device.
2. Active negation outputs only: Data, Parity, SREQ/, SACK/. (Minus Pins) SCSI mode only.
3. Single pin only; irreversible damage may occur if sustained for one second.
4. SCSI RESET pin has 10 k $\Omega$  pull-up resistor.

**Figure 3.7 Rise and Fall Time Test Conditions**



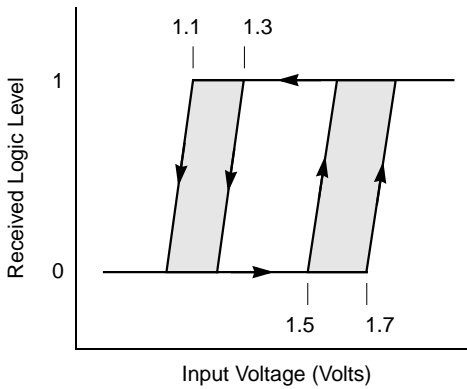


**Figure 3.8 SCSI Input Filtering**

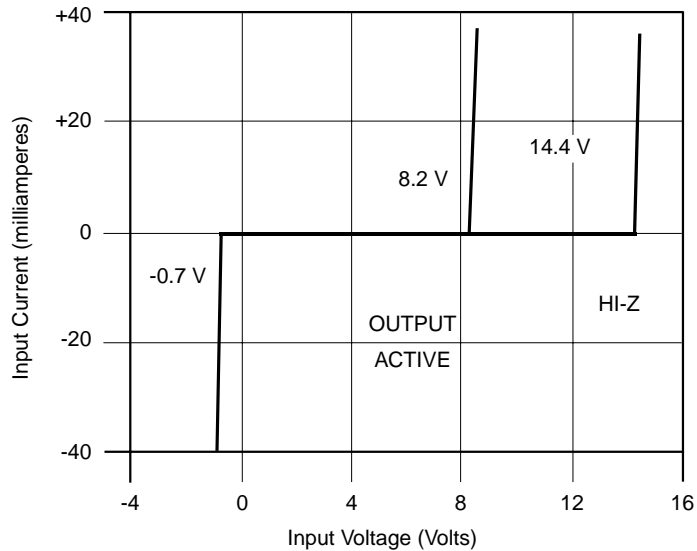


Note:  $t_1$  is the input filtering period.

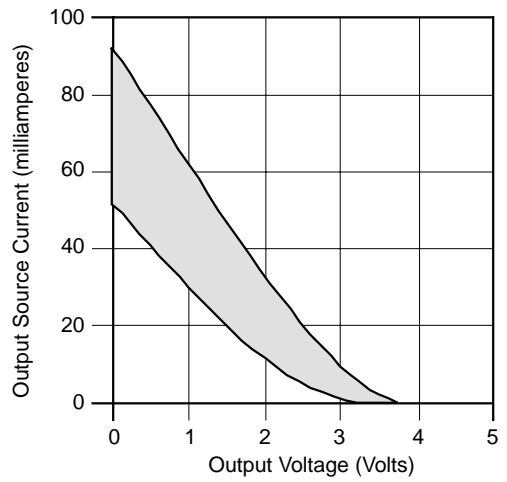
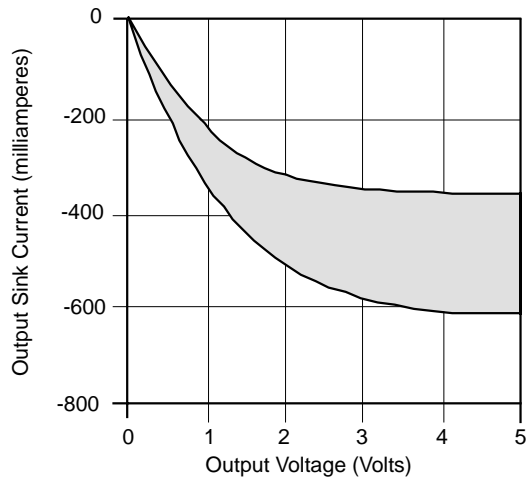
**Figure 3.9 Hysteresis of SCSI Receivers**



**Figure 3.10 Input Current as a Function of Input Voltage**



**Figure 3.11 Output Current as a Function of Output Voltage**



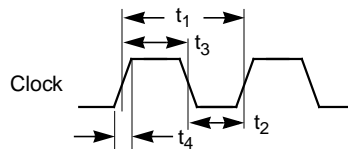
### 3.2.3 AC Characteristics

The AC characteristics described in this section apply over the entire range of operating conditions (refer to DC Characteristics in this chapter). Chip timing is based on simulation at worst case voltage, temperature, and processing. The LSI53C180 requires a 40 MHz clock input.

**Table 3.16 Clock Timing**

Symbol	Parameter	Min	Max	Units
$t_1$	Clock period	24.75	25.25	ns
$t_2$	Clock low time	10	15	ns
$t_3$	Clock high time	10	15	ns
$t_4$	Clock rise time	1	–	V/ns

**Figure 3.12 Clock Timing**



### 3.2.4 SCSI Interface Timing

**Table 3.17 Input Timing - Single Transition**

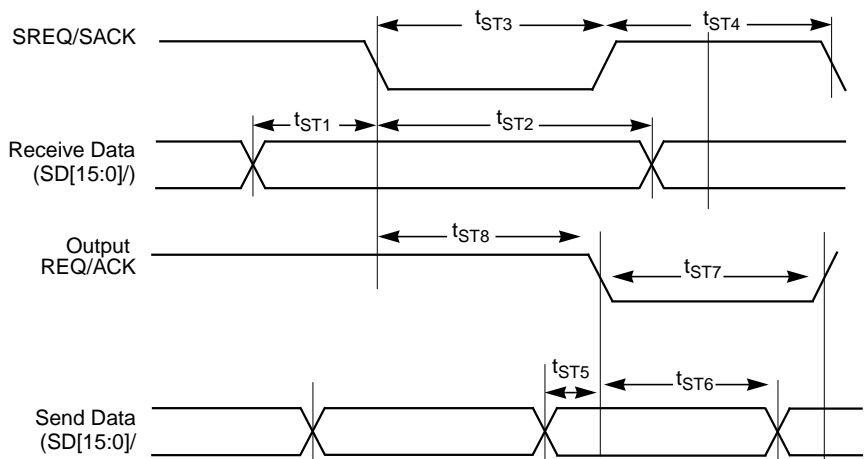
Symbol	Parameter	Min	Max	Units
$t_{ST1}$	Input data setup	4.5	–	ns
$t_{ST2}$	Input data hold	4.5	–	ns
$t_{ST3}$	Input REQ/ACK assertion pulse width	6.5	–	ns
$t_{ST4}$	Input REQ/ACK deassertion pulse width	6.5	–	ns

**Table 3.18 Output Timing - Single Transition**

Symbol	Parameter	Min	Max	Units
$t_{ST5}$	Output data setup	Nominal: negotiated/2	–	ns
$t_{ST6}$	Output data hold	Nominal: negotiated/2	–	ns
$t_{ST7}$	Output REQ/ACK pulse width	max [negotiated ns, $t_{ST3} - 5$ ]	max [negotiated ns, $t_{ST3} + 5$ ]	ns
$t_{ST8}$	REQ/ACK transport delay	25 ns if REQ/ACK is clock for input data, 10 ns if not	50 ns if REQ/ACK is clock for input data, 30 ns if not	ns

Note: Pulse width is a negotiated value and ranges from 12.5 to over 1000 ns.

**Figure 3.13 Input/Output Timing - Single Transition**



**Table 3.19 Input Timing - Double Transition**

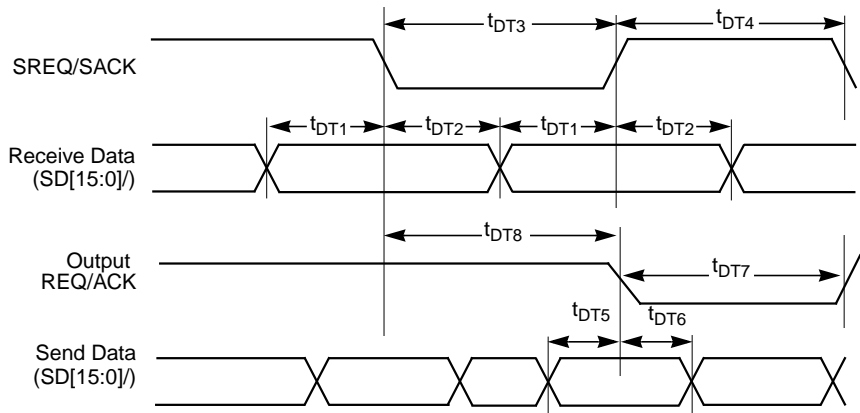
Symbol	Parameter	Min	Max	Units
$t_{DT1}$	Input data setup	1.25	–	ns
$t_{DT2}$	Input data hold	1.25	–	ns
$t_{DT3}$	Input REQ/ACK assertion pulse width	10	–	ns
$t_{DT4}$	Input REQ/ACK deassertion pulse width	10	–	ns

**Table 3.20 Output Timing - Double Transition**

Symbol	Parameter	Min	Max	Units
$t_{DT5}$	Output data setup	Nominal: negotiated/2	–	ns
$t_{DT6}$	Output data hold	Nominal: negotiated/2	–	ns
$t_{DT7}$	Output REQ/ACK pulse width	max [negotiated ns, $t_{DT3} - 5$ ]	max [negotiated ns, $t_{DT3} + 5$ ]	ns
$t_{DT8}$	REQ/ACK transport delay	25 ns if REQ/ACK is clock for input data, 10 ns if not	50 ns if REQ/ACK is clock for input data, 30 ns if not	ns

Note: Pulse width is a negotiated value and ranges from 12.5 to over 1000 ns.

**Figure 3.14 Input/Output Timing - Double Transition**



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### 3.3 Mechanical Drawings

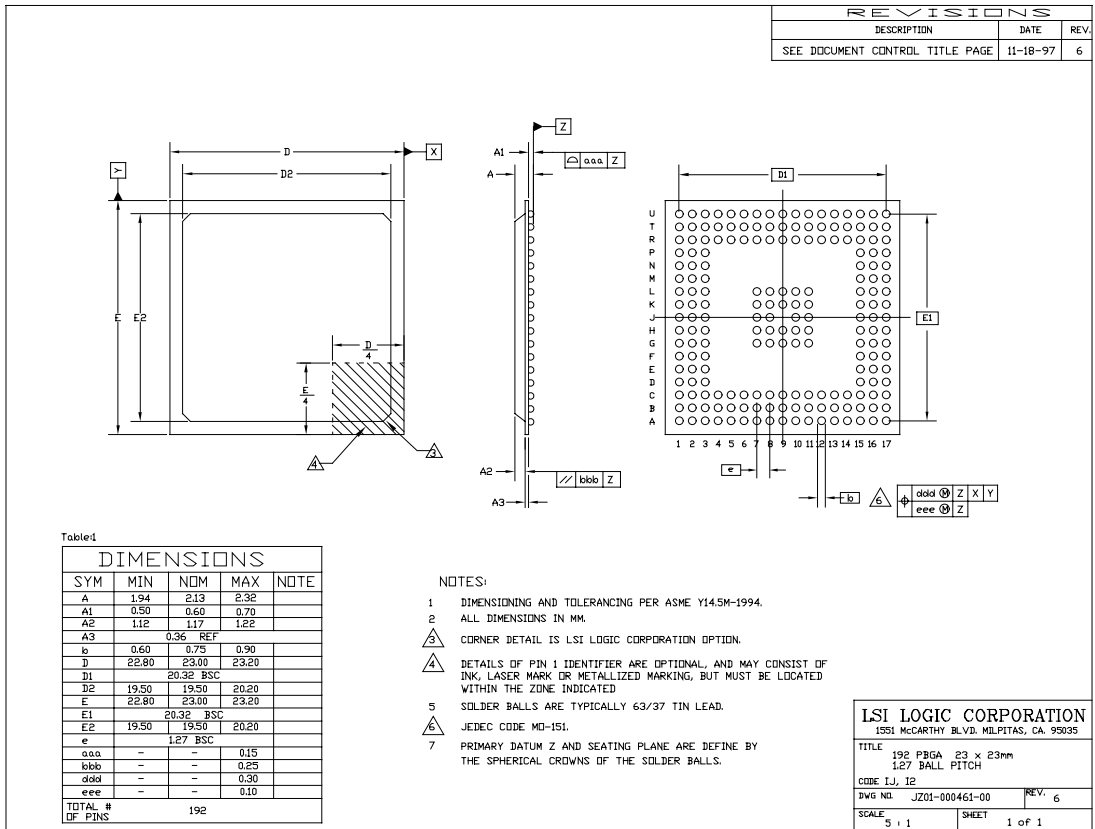
LSI Logic component dimensions conform to a current revision of the JEDEC Publication 95 standard package outline, using ANSI 14.5Y “Dimensioning and Tolerancing” interpretations. As JEDEC drawings are balloted and updated, changes may have occurred. To ensure the use of a current drawing, the JEDEC drawing revision level should be verified. Visit [www.jedec.org](http://www.jedec.org) representing the Solid State Technology Association. Search for Publication 95 and click on MO Mechanical Outlines for drawings and revision levels.

For printed circuit board land patterns that will accept LSI Logic components, it is recommended that customers refer to the IPC standards (Institute for Interconnecting and Packaging Electronic Circuits). Specification number IPC-SM-782, “Surface Mount Design and Land Pattern Standard” is an established method of designing land patterns. Feature size and tolerances are industry standards based on IPC assumptions.

### 3.3.1 LSI53C180 192-Pin BGA Mechanical Drawing

The LSI53C180 is packaged in a 192-pin Plastic Ball Grid Array (PBGA).

Figure 3.15 192-Pin PBGA (IJ, I2) Mechanical Drawing



**Important:** This drawing may not be the latest version. For board layout and manufacturing, obtain the most recent engineering drawings from your LSI Logic marketing representative by requesting the outline drawing for package code IJ, I2.





# Appendix A

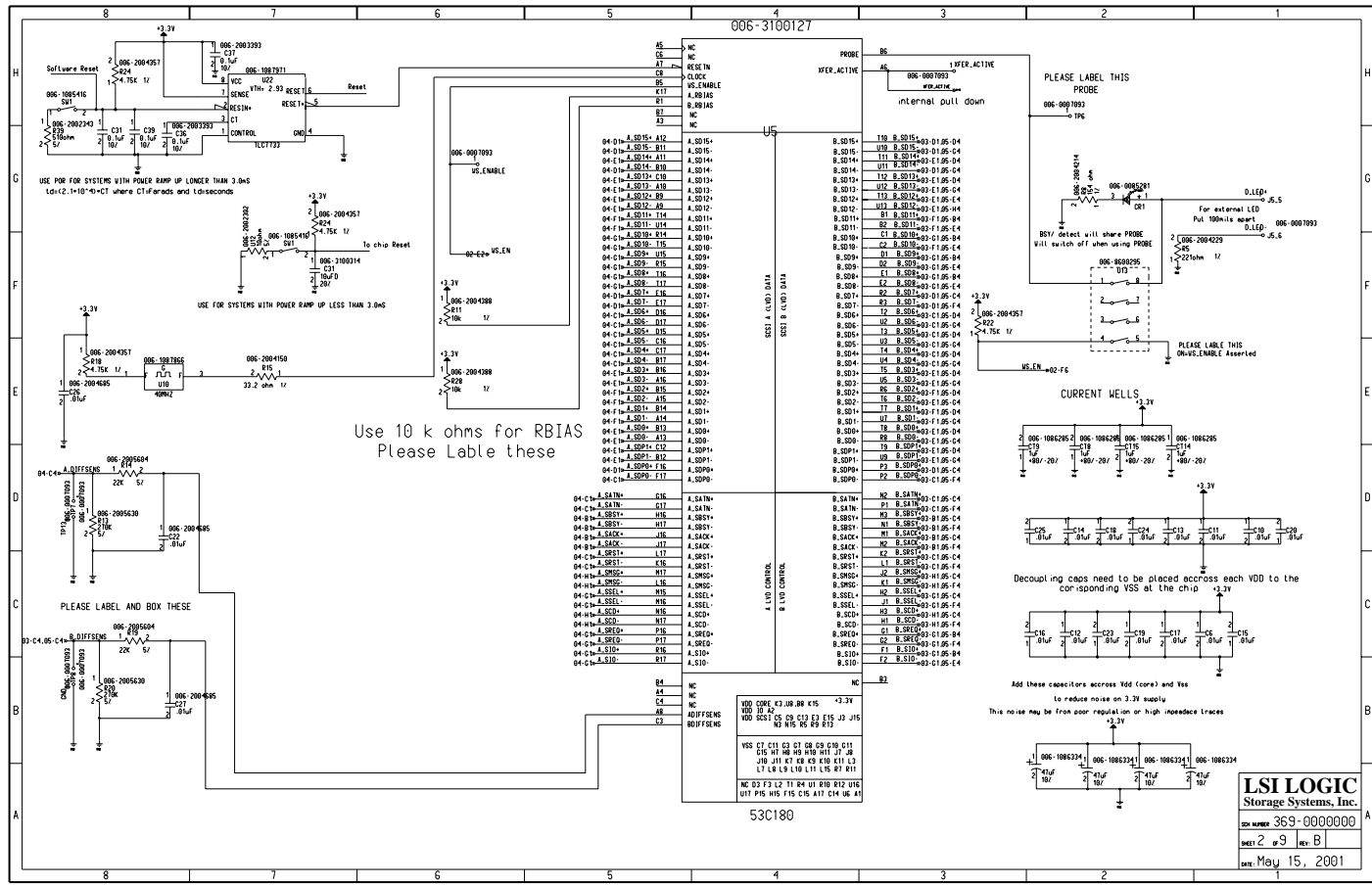
## Wiring Diagrams

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### A.1 LSI53C180 Wiring Diagrams

The following four pages of wiring diagrams are of a typical LSI53C180 in a evaluation test board application.

Figure A.1 LSI53C180 Wiring Diagram 1 of 4











# Appendix B

## Glossary

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<b>ACK/</b>	Acknowledge – Driven by an initiator, ACK/ indicates an acknowledgment or a SCSI data transfer. In the target mode, ACK/ is received as a response to the REQ/ signal.
<b>ANSI</b>	American National Standards Institute.
<b>Arbitration</b>	The process of selecting one respondent from a collection of several candidates that request service concurrently.
<b>Asserted</b>	A signal is asserted when it is in the state that is indicated by the name of the signal. Opposite of negated or deasserted.
<b>Assertion</b>	The act of driving a signal to the true state.
<b>Asynchronous Transmission</b>	Transmission in which each byte of the information is synchronized individually through the use of Request (REQ/) and Acknowledge (ACK/) signals.
<b>ATN/</b>	Attention – Driven by an initiator, indicates an attention condition. In the target role, ATN/ is received and is responded to by entering the Message Out Phase.
<b>Block</b>	A block is the basic 512 byte size of storage that the storage media is divided into. The Logical Block Address protocol uses sequential block addresses to access the media.
<b>BSY/</b>	Busy – Indicates that the SCSI Bus is being used. BSY/ can be driven by the initiator or the target device.
<b>Bus</b>	A collection of unbroken signal lines that interconnect computer modules. The connections are made by taps on the lines.
<b>Bus Expander</b>	Bus expander technology permits the extension of a bus by providing some signal filtering and retiming to maintain signal skew budgets.

<b>Cable Skew Delay</b>	Cable skew delay is the minimum difference in propagation time allowed between any two SCSI bus signals measured between any two SCSI devices.
<b>C_D/</b>	Control/Data – Driven by a target. When asserted, indicates Control or Data Information is on the SCSI Bus. This signal is received by the initiator.
<b>Connect</b>	The function that occurs when an initiator selects a target to start an operation, or a target reselects an initiator to continue an operation.
<b>Control Signals</b>	The set of nine lines used to put the SCSI bus into its different phases. The combinations of asserted and negated control signals define the phases.
<b>Controller</b>	A computer module that interprets signals between a host and a peripheral device. Often, the controller is a part of the peripheral device, such as circuitry on a disk drive.
<b>DB[7:0]/</b>	SCSI Data Bits – These eight Data Bits (DB[7:0]/), plus a Parity Bit (DBP/), form the SCSI bus. DB7/ is the most significant bit and has the highest priority ID during the Arbitration Phase. Data parity is odd. Parity is always generated and optionally checked. Parity is not valid during arbitration.
<b>Deasserted</b>	The act of driving a signal to the false state or allowing the cable terminators to bias the signal to the false state (by placing the driver in the high impedance condition).  A signal is deasserted or negated when it is in the state opposite to that which is indicated by the name of the signal. Opposite of asserted.
<b>Device</b>	A single unit on the SCSI bus, identifiable by a SCSI address. It can be a processor unit, a storage unit (such as a disk or tape controller or drive), an output unit (such as a controller or printer), or a communications unit.
<b>Differential</b>	A signaling alternative that employs differential drivers and receivers to improve signal-to-noise ratios and increase maximum cable lengths.
<b>Disconnect</b>	The function that occurs when a target releases control of the SCSI bus, allowing the bus to go to the Bus Free phase.
<b>Driver</b>	When used in the context of electrical configuration, “driver” is the circuitry that creates a signal on a line.



<b>External Configuration</b>	All SCSI peripheral devices are external to the host enclosure.
<b>External Terminator</b>	The terminator that exists on the last peripheral device that terminates the end of the external SCSI bus.
<b>Free</b>	In the context of Bus Free phase, “free” means that no SCSI device is actively using the SCSI bus and, therefore, the bus is available for use.
<b>Host</b>	A processor, usually consisting of the central processing unit and main memory. Typically, a host communicates with other devices, such as peripherals and other hosts. On the SCSI bus, a host has a SCSI address.
<b>Host Adapter</b>	Circuitry that translates between a processor's internal bus and a different bus, such as SCSI. On the SCSI bus, a host adapter usually acts as an initiator.
<b>Initiator</b>	A SCSI device that requests another SCSI device (a target) to perform an operation. Usually, a host acts as an initiator and a peripheral device acts as a target.
<b>Internal Configuration</b>	All SCSI peripheral devices are internal to the host enclosure.
<b>Internal Terminator</b>	The terminator that exists within the host that terminates the internal end of the SCSI bus.
<b>I/O</b>	Input/Output – Driven by a target. I/O controls the direction of data transfer on the SCSI bus. When active, this signal indicates input to the initiator. When inactive, this signal indicates output from the initiator. This signal is also used to distinguish between the Selection and Reselection Phases.
<b>I/O Cycle</b>	An I/O cycle is an Input (I/O Read) operation or Output (I/O Write) operation that accesses the PC Card's I/O address space.
<b>Logical Unit</b>	The logical representation of a physical or virtual device, addressable through a target. A physical device can have more than one logical unit.
<b>Low (logical level)</b>	A signal is at the low logic level when it is below approximately 0.5 volts.

<b>LSB</b>	Abbreviation for Least Significant Bit or Least Significant Byte. That portion of a number, address or field that occurs right-most when its value is written as a single number in conventional hexadecimal or binary notation. The portion of the number having the least weight in a mathematical calculation using the value.
<b>LUN</b>	Logical Unit Number. Used to identify a logical unit.
<b>LVD</b>	Low Voltage Differential. LVD is a robust design methodology that improves power consumption, data integrity, cable lengths and support for multiple devices, while providing a migration path for increased I/O performance.
<b>Mandatory</b>	A characteristic or feature that must be present in every implementation of the standard.
<b>MHz</b>	MegaHertz – Measurement in millions of Hertz per second. Used as a measurement of data transfer rate.
<b>microsecond (<math>\mu</math>s)</b>	One millionth of a second.
<b>MSB</b>	Abbreviation for Most Significant Bit or Most Significant Byte. That portion of a number, address or field that occurs left-most when its value is written as a single number in conventional hexadecimal or binary notation. The portion of the number having the most weight in a mathematical calculation using the value.
<b>MSG/</b>	Message – Driven active by a target during the Message Phase. This signal is received by the initiator.
<b>nanosecond (ns)</b>	One billionth of a second.
<b>Negated</b>	A signal is negated or deasserted when it is in the state opposite to that which is indicated by the name of the signal. Opposite of asserted.
<b>Negation</b>	The act of driving a signal to the false state or allowing the cable terminators to bias the signal to the false state.
<b>Parity</b>	A method of checking the accuracy of binary numbers. An extra bit, called a parity bit, is added to a number. If even parity is used, the sum of all 1s in the number and its corresponding parity is always even. If odd parity is used, the sum of the 1s and the parity bit is always odd.
<b>Peripheral Device</b>	A device that can be attached to the SCSI bus. Typical peripheral devices are disk drives, tape drives, printers, CD ROMs, or communications units.

<b>Phase</b>	One of the eight states to which the SCSI bus can be set. During each phase, different communication tasks can be performed.
<b>Port</b>	A connection into a bus.
<b>Priority</b>	The ranking of the devices on the bus during arbitration.
<b>Protocol</b>	A convention for data transmission that encompasses timing control, formatting, and data representation.
<b>Receiver</b>	The circuitry that receives electrical signals on a line.
<b>Reconnect</b>	The function that occurs when a target reselects an initiator to continue an operation after a disconnect.
<b>Release</b>	The act of allowing the cable terminators to bias the signal to the false state (by placing the driver in the high impedance condition).
<b>REQ/</b>	Request – Driven by a target, indicates a request for a SCSI data-transfer handshake. This signal is received by the initiator.
<b>Reselect</b>	A target can disconnect from an initiator in order to perform a time-consuming function, such as a disk seek. After performing the operation, the target can “reselect” the initiator.
<b>RESET</b>	Reset – Clears all internal registers when active. It does not assert the SCSI RST/ signal and therefore does not reset the SCSI bus.
<b>RST</b>	Reset – Indicates a SCSI Bus reset condition.
<b>SCSI Address</b>	The octal representation of the unique address ([7:0]) assigned to an SCSI device. This address is normally assigned and set in the SCSI device during system installation.
<b>SCSI ID (Identification) or SCSI Device ID</b>	The bit-significant representation of the SCSI address referring to one of the signal lines DB7/ through DB0/.
<b>SCSI</b>	Small Computer System Interface.
<b>SCAM</b>	An acronym for SCSI Configured AutoMatically. SCAM is the new SCSI automatic ID assignment protocol. SCAM frees SCSI users from locating and setting SCSI ID switches and jumpers. SCAM is the key part of Plug and Play SCSI.
<b>SEL/</b>	Select – Used by an initiator to select a target, or by a target to reselect an initiator.

<b>Single-Ended Configuration</b>	An electrical signal configuration that uses a single line for each signal, referenced to a ground path common to the other signal lines. The advantage of a single-ended configuration is that it uses half the pins, chips, and board area that differential/low-voltage differential configurations require. The main disadvantage of single-ended configurations is that they are vulnerable to common mode noise. Also, cable lengths are limited.
<b>Synchronous Transmission</b>	Transmission in which the sending and receiving devices operate continuously at the same frequency and are held in a desired phase relationship by correction devices. For buses, synchronous transmission is a timing protocol that uses a master clock and has a clock period.
<b>Target</b>	A SCSI device that performs an operation requested by an initiator.
<b>Termination</b>	The electrical connection at each end of the SCSI bus, composed of a set of resistors.
<b>Ultra3 SCSI</b>	A standard for SCSI data transfers. It allows a transfer rate of up to 160 Mbytes/s over a 16-bit SCSI bus. STA (SCSI Trade Association) supports using the terms "Ultra3 SCSI" over the term "Fast-80."

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Alpharetta, GA 30004  
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Bethesda, MD 20817  
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Waltham, MA 02451  
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### New York

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Building 1  
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Austin, TX 78759  
Tel: 512.388.7294  
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### Plano

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Suite 440  
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◆ **LSI Logic K.K.**  
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### **LSI Logic Corporation of Korea Ltd**

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### **LSI Logic Europe Ltd**

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Singapore

### **LSI Logic Pte Ltd**

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### **LSI Logic AB**

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◆ Sales Offices with  
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Fax: 852.2401.2105

## Serial System (HK) Ltd

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57 Hung To Road, Kwun Tong  
Kowloon, Hong Kong  
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## India

Bangalore  
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Fax: 81.3.3261.3984

## Global Electronics Corporation

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## Marubeni Solutions

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## Shinki Electronics

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## Macnica Corporation

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## Prospect Technology Corporation, Ltd

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## Milton Keynes

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